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April 2025

# FQP13N10L

# N-Channel QFET® MOSFET

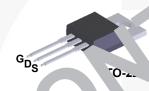
100 V, 12.8 A, 180  $m\Omega$ 

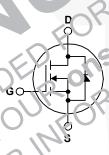
# **Description**

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

#### **Features**

- 12.8 A, 100 V,  $R_{DS(on)}$  = 180 m $\Omega$  (Max.) @  $V_{GS}$  = 10 V,  $I_D$  = 6.4 A
- · Low Gate Charge (Typ. 8.7 nC)
- · Low Crss (Typ. 20 pF)
- 100% Avalanche Trated
- 175°C Maximum Jun חור are Rating.





# Absolute Max num Tatings To = 20 C unless of the raise noted

Symbo	Parameter	FQP13N10L	Unit	
V <sub>DS</sub>	Jair ource Voltage	100	V	
	Curren - Continuous (T) = 25°C)	12.8	Α	
	- Continuous (T <sub>C</sub> = 100°C)	9.05	A	
I <sub>DM</sub>	Drain Current Pulsed (Note 1)	51.2	A	
1 5	Gats-Source Voltage	± 20	V	
⊏AS	Single Pulsar Avalanche Energy (Note 2)	95	mJ	
IAR	Avalanche Cur en: (Note 1)	12.8	Α	
EAR	Repetitive A valar che Energy (Note 1)	6.5	mJ	
dv/dt	Peak Dic de Recovery dv/dt (Note 3)	6.0	V/ns	
$P_{D}$	Power Dissipation (T <sub>C</sub> = 25°C)	65	W	
	- Derate above 25°C	0.43	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +175	°C	
TL	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.	300	°C	

### **Thermal Characteristics**

Symbol	Parameter	FQP13N10L	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.31	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQP13N10L	FQP13N10L	TO-220	Tube	N/A	N/A	50 units

# **Electrical Characteristics**

T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	racteristics					
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100			V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 μA, Referenced to 25°C		0.09		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V V <sub>DS</sub> = 80 V, T <sub>C</sub> = 150°C			1	μ <b>Α</b> μ <b>Α</b>
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -20 V, V <sub>DS</sub> = 0 V	-	-	-100	nA
On Cha	racteristics		T			
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1.0		2.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 6.4$ $V_{GS} = 5 \text{ V}, I_D = 9.4 \text{ A}$		0.142 0.152	0 18 0.2	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 30 ' I <sub>D</sub>		9.5	1	S
Dynami	ic Characteristics		7	66	$U_{II}$	OL
C <sub>iss</sub>	Input Capacitance	$V_{DS} = V, V_{GS} = 0 V,$	(	400	52U	pF
C <sub>oss</sub>	Output Capacitance	= 1.0 M	0	95	125	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	VEL TIL		50	25	pF
Switchi	ing Characteristi	- WWW. 1001	50	)`		
t <sub>d(on)</sub>	Turn-On D , ine	ν <sub>DD</sub> = 50 V, I <sub>D</sub> = 12.8 A		7.5	25	ns
t <sub>r</sub>	Turn-On se Time	$R_G = 25.5$		220	450	ns
$t_{d(off)}$	7 Off L by Tim	171.50.		22	55	ns
t <sub>f</sub>	furn CT Fall .	(Note 4)		72	150	ns
$Q_g$	rotal Gat Charge	V <sub>DS</sub> = δ0 /, ι <sub>D</sub> = 12.8 A,		8.7	12	nC
	Ga. Jurce Chargo	V <sub>GS</sub> = 5 V		2.0		nC
Q <sub>gd</sub>	ate-Drain Cinarge	(Note 4)	/	5.3		nC
ın-Ş	ource Diode Characterizace ar	nd Maximum Ratings				
ls	Maximum Continuous Orgin Source Diode Forward Current				12.8	Α
!SN'	Maximum Pulsed Drain-Source Diode Forward Current				51.2	Α
V <sub>SD</sub>	Drain-Source Dinde Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 12.8 A			1.5	V
t <sub>rr</sub>	Revers : Fecovery Time	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 12.8 A,		75	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl <sub>F</sub> / dt = 100 A/μs		0.17	//	μС

- Notes: 1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 0.87 mH, I<sub>AS</sub> = 12.8 A, V<sub>DD</sub> = 25 V, R<sub>G</sub> = 25  $\Omega$  starting T<sub>J</sub> = 25°.C 3. I<sub>SD</sub>  $\leq$  12.8 A, di/dt  $\leq$  300 A/ $\mu$ s, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, starting T<sub>J</sub> = 25°C. 4. Essentially independent of operating temperature.

# **Typical Characteristics**

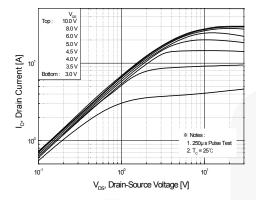


Figure 1. On-Region Characteristics

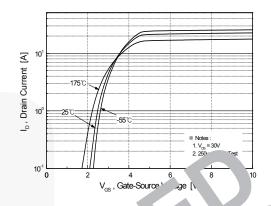
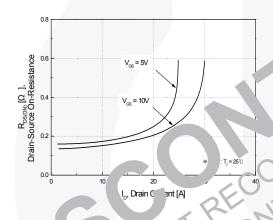


Figure 2. 1. sfe maractiristics



F ... n-Resistance Variation vs.
Drain / prent and Gate Voltage

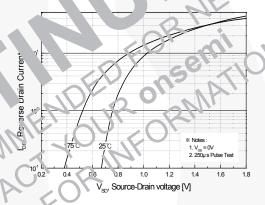


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

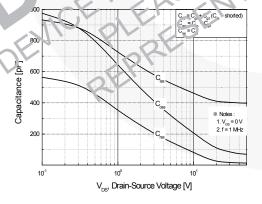


Figure 5. Capacitance Characteristics

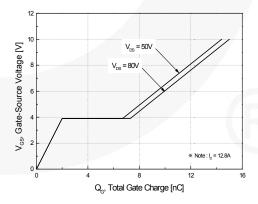


Figure 6. Gate Charge Characteristics

# Typical Characteristics (Continued)

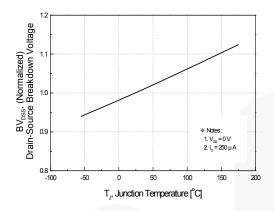
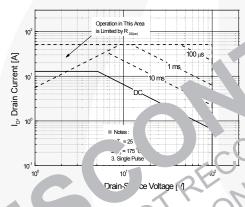


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. Re cance 'ariation vs. mp of a



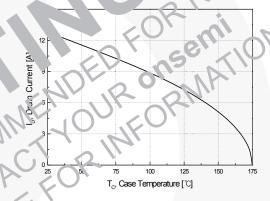


Figure 9. I iximum (lafe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

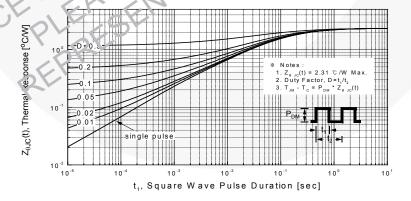


Figure 11. Transient Thermal Response Curve

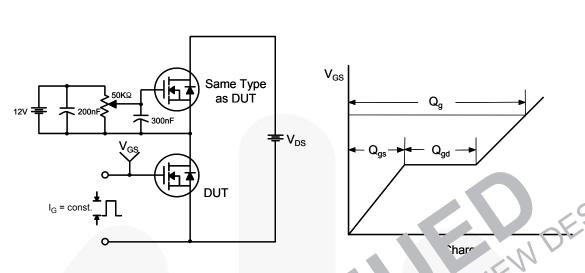


Figure 12. Gate Charge Test Circu & avefc n

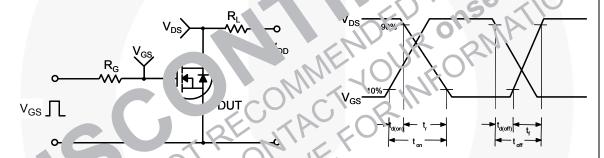


Figure 13. Resistive Switching Test Circuit & Waveforms

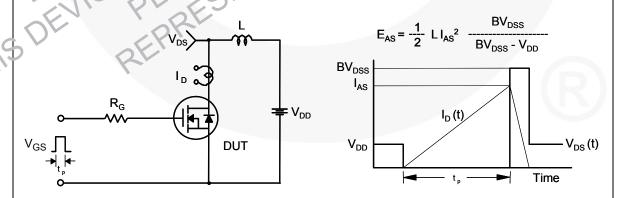
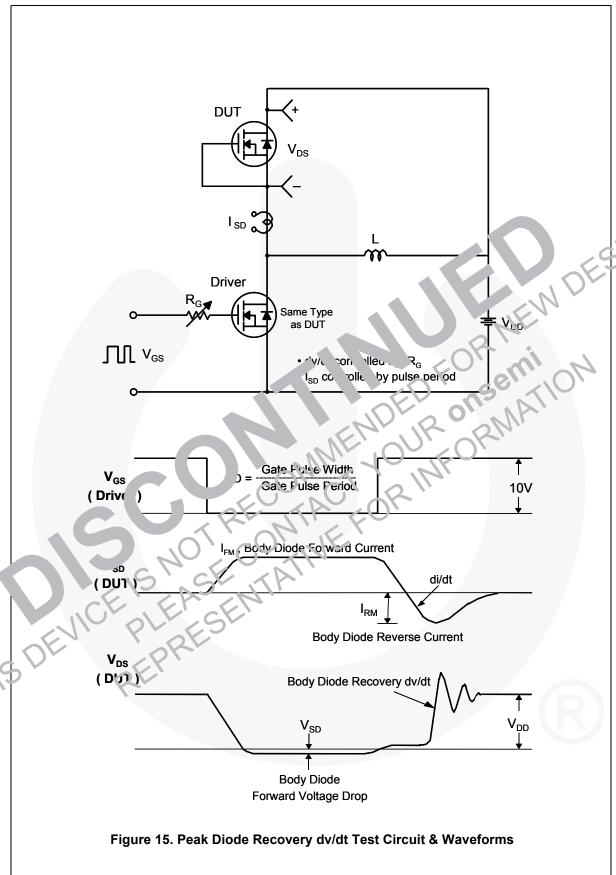


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



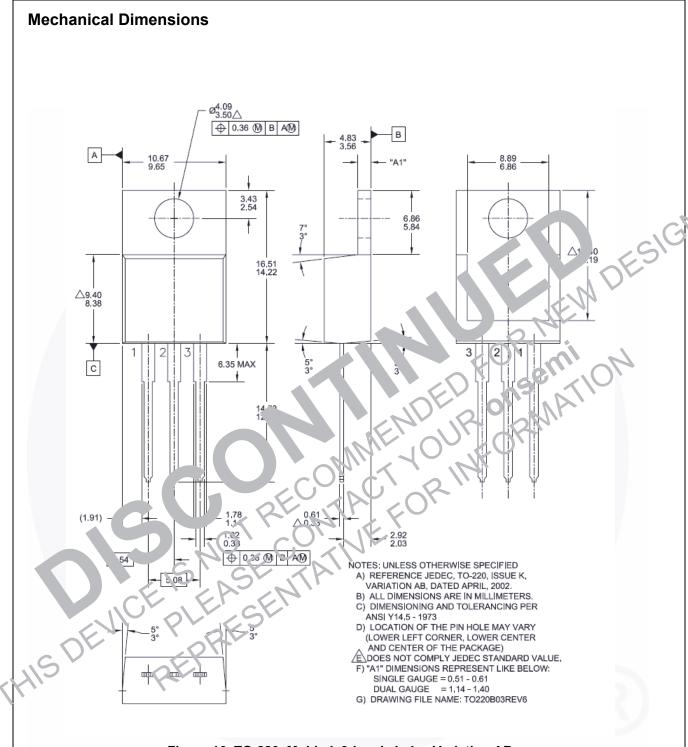


Figure 16. TO-220, Molded, 3-Lead, Jedec Variation AB

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